

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	27	((SYUUJI) near2 (EGUCHI)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/29 13:13
S2	328	((MASAHIKO) near2 (ASANO)).INV.	EPO; JPO; DERWENT	AND	ON	2007/10/29 13:13
S3	46	((MASAHIKO) near2 (ASANO)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/29 13:13
S4	328	((MASAHIKO) near2 (ASANO)).INV.	EPO; JPO; DERWENT	AND	ON	2007/10/29 13:13
S5	48	((MASAHIRO) near2 (SASAKI)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/29 13:13
S6	545	((MASAHIRO) near2 (SASAKI)).INV.	EPO; JPO; DERWENT	AND	ON	2007/10/29 13:13
S7	69	((KAORU) near2 (UCHIYAMA)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/29 13:13
S8	299	((KAORU) near2 (UCHIYAMA)).INV.	EPO; JPO; DERWENT	AND	ON	2007/10/29 13:14
S9	181	S1 S2 S3 S4 S5 S6 S7 S8	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/29 13:15
S10	50	(US-4614559-\$ or US-5596663-\$ or US-5783134-\$ or US-RE36886-\$ or US-4992849-\$ or US-4992850-\$ or US-5233676-\$ or US-5266834-\$ or US-5384683-\$ or US-5466969-\$ or US-5541368-\$ or US-5583375-\$ or US-5612532-\$ or US-5668702-\$ or US-5714405-\$ or US-5726491-\$ or US-5742477-\$ or US-5803761-\$ or US-5808872-\$ or US-5854558-\$ or US-5869888-\$ or US-5875047-\$ or US-5910010-\$ or US-RE36325-\$ or US-6144571-\$ or US-6169325-\$).did. or (US-4495546-\$ or US-4592014-\$ or US-4632662-\$ or US-4780791-\$ or US-4783345-\$ or US-4798117-\$ or US-4847979-\$ or US-4857482-\$ or US-4873123-\$ or US-4914883-\$ or US-4932117-\$ or US-4974120-\$ or US-4984352-\$ or US-4985747-\$ or US-4989318-\$ or US-4994659-\$ or US-5025307-\$ or US-5179601-\$ or US-5180888-\$ or US-5182853-\$ or US-5206074-\$ or US-5206783-\$ or US-5221420-\$ or US-5272374-\$).did.	USPAT	AND	ON	2007/10/29 13:15
S11	35	connector (PCB or wcb or ((circuit or wiring) adj board)) (thermosetting adj resin) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:31

S12	1	S9 S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:19
S13	0	S10 S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:19
S14	3787	(thermosetting adj resin) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:32
S15	502	(PCB or wcb or ((circuit or wiring) adj board)) (thermosetting adj resin) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:21
S16	35	connector (PCB or wcb or ((circuit or wiring) adj board)) (thermosetting adj resin) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:28
S17	38	connector (PCB or wcb or ((circuit or wiring) adj board)) (thermoset\$4 adj resin) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/31 08:03
S18	3	S17 not S16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:29
S19	13697	connector near (PCB or wcb or ((circuit or wiring) adj board))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 17:16
S20	4281	(thermoset\$4 adj resin) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 17:22
S21	25	(thermoset\$4 adj resin) (solid near resin) ppm GPa	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:36

S22	73	((thermoset\$4 adj resin) (solid near resin) ((expansion adj coefficient) or "ppm/°C") (modulus or elasticity or GPa) ((transition adj temperature) or (degree or "°C"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 16:21
S23	88	S21 S22	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/29 13:42
S24	0	((thermoset\$4 adj resin) ((solid adj stste) near (degree or "°C")) ((solid adj stste) near below)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:47
S25	0	((thermoset\$4 adj resin) ((solid adj state) near (degree or "°C")) ((solid adj state) near below)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:47
S26	0	((thermoset\$4 adj resin) ((solid adj state) near (degree or "°C")) ((solid adj state) near below)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:47
S27	12	((thermoset\$4 adj resin) ((solid adj state) near (degree or "°C"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:47
S28	559	((thermoset\$4 adj resin) (solid near (degree or "°C"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 12:12
S29	3	((thermoset\$4 adj resin) (solid near (degree or "°C")) (solid near below)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:49
S30	93	((thermoset\$4 adj resin) (solid near (degree or "°C")) (solid with below)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 13:49
S31	90	S28 S30	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/29 15:19
S32	7	resin near molding near (different adj (thickness or height))	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/29 15:20
S33	0	((thermoset\$4 adj resin) ((expansion adj coefficient) and "ppm/°C") ((modulus or elasticity or molding) with GPa) ((transition adj temperature) and (degree or "°C"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 16:22

S34	0	((thermoset\$4 adj resin) ((expansion adj coefficient) and "ppm/ °C" ((modulus or elasticity or molding) near GPa) ((transition adj temperature) and (degree or "°C"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 16:50
S35	4	((thermoset\$4 adj resin) ((expansion adj coefficient) and "ppm/ °C")	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 16:23
S36	240	((thermoset\$4 adj resin) ((modulus or elasticity or molding) near GPa)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 16:29
S37	239	((thermoset\$4 adj resin) ((modulus or elasticity) near GPa)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 16:28
S38	32	((thermoset\$4 adj resin) ((modulus or elasticity or molding) near GPa) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 16:29
S39	140	((thermoset\$4 adj resin) ((transition adj temperature) near (degree or "°C"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 16:50
S40	765	((thermoset\$4 adj resin) ((glass adj transition adj temperature) near (degree or "°C"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 12:10
S41	64	((thermoset\$4 adj resin) ((glass adj transition adj temperature) near (degree or "°C")) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 14:44
S42	765	((device or package) ((edge adj connector) near (PCB or wcb or ((circuit or wiring) adj board)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 17:21
S43	0	S20 S42	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/29 17:18

S44	4	S42 (thermoset\$4 adj resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 17:19
S45	7619	(device or package) ((connector) near (PCB or wcb or ((circuit or wiring) adj board)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/31 08:02
S46	1	S20 S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 17:22
S47	59	(thermoset\$4 adj resin) S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/29 17:22
S48	0	("2005/0057902").URPN.	USPAT	AND	ON	2007/10/29 17:31
S49	0	("2006/0077643").URPN.	USPAT	AND	ON	2007/10/29 17:32
S50	0	("2006/0272150").URPN.	USPAT	AND	ON	2007/10/29 17:33
S51	38	connector (PCB or wcb or ((circuit or wiring) adj board)) (thermoset\$4 adj resin) (solid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:06
S52	75	connector near (PCB or wcb or ((circuit or wiring) adj board)) (thermoset\$4 adj resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:07
S53	75	(connector near (PCB or wcb or ((circuit or wiring) adj board))) (thermoset\$4 adj resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:10
S54	73	S53 not S51	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:07
S55	254	(connector near (PCB or wcb or ((circuit or wiring) adj board))) (resin with molding)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:45

S56	210	S55 not S53 not S51	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 09:11
S57	10	((connector near (PCB or wcb or ((circuit or wiring) adj board)) near component) (resin with molding)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:45
S58	0	((side adj connector) near (PCB or wcb or ((circuit or wiring) adj board)) near component) (resin with molding)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:45
S59	4	((side adj connector) near (PCB or wcb or ((circuit or wiring) adj board))) (resin with molding)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:57
S60	82	((side adj connector) near (PCB or wcb or ((circuit or wiring) adj board)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:58
S61	0	(side adj connector) near (PCB or wcb or ((circuit or wiring) adj board)) near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 09:59
S62	33	(edge adj connector) near (PCB or wcb or ((circuit or wiring) adj board)) near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 10:12
S63	0	(side near connector) near (PCB or wcb or ((circuit or wiring) adj board)) near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 10:12
S64	5	(side near connector) near (PCB or wcb or ((circuit or wiring) adj board)) with component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 10:14
S65	1743	(side near connector) ((PCB or wcb or ((circuit or wiring) adj board)) with component)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 10:15

S66	116	(side near connector) with ((PCB or wcb or ((circuit or wiring) adj board)) with component)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 10:28
S67	4	(side near connector) with ((PCB or wcb or ((circuit or wiring) adj board)) with component) (thermoset\$4 adj resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 10:15
S68	8	("20020062698" "20020154466" "20050206357" "5285010" "5699235" "5957547" "6282092" "6875029").PN.	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 10:17
S69	544	(thermoset\$4 adj resin) ((glass adj transition adj temperature) near (degree or "°C")) (inorganic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 12:11
S70	280	(thermoset\$4 adj resin) (solid near (degree or "°C")) (inorganic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 12:13
S71	60	(US-20020181211-\$ or US-20040030123-\$ or US-20030236347-\$ or US-20040195826-\$ or US-20030159764-\$ or US-20030116269-\$ or US-20020111707-\$ or US-20020086104-\$ or US-20020113331-\$ or US-20050227067-\$ or US-20030082315-\$ or US-20040044134-\$ or US-20040247882-\$ or US-20020010288-\$ or US-20020126457-\$ or US-20050057902-\$ or US-20060077643-\$ or US-20040047570-\$ or US-20030053767-\$ or US-20030104729-\$).did. or (US-4486466-\$ or US-5364914-\$ or US-4972031-\$ or US-5528155-\$ or US-4042486-\$ or US-3619342-\$ or US-4524161-\$ or US-3919348-\$ or US-3919134-\$ or US-3907724-\$ or US-6314253-\$ or US-6222006-\$ or US-4446257-\$ or US-3617429-\$ or US-3607598-\$ or US-4119679-\$ or US-3616163-\$ or US-4147737-\$ or US-5385957-\$ or US-5540581-\$ or US-5232654-\$ or US-5672305-\$ or US-5464658-\$ or US-5350621-\$ or US-6713598-\$ or US-6415104-\$).did. or (US-4548678-\$ or US-6043333-\$ or US-5743751-\$ or US-5957547-\$ or US-5699235-\$ or US-6282092-\$).did. or (US-3772392-\$ or US-2983630-\$ or US-2935488-\$ or US-3484398-\$ or US-3838087-\$ or US-3300332-\$ or US-3510445-\$ or US-3331891-\$).did.	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 14:23
S72	23413	(BGA or CSP)	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 14:24

S73	0	S71 S72	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 14:24
S74	21	(BGA or CSP) ((through adj hole) near mm)	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 14:42
S75	241365	power near2 (chip or IC or transistor or device)	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 14:43
S76	3	S71 S75	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 14:43
S77	2	"20040062015".did.	US-PGPUB; USPAT; USOCR; FPRS; EPC; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/30 14:45
S78	61	(US-20020181211-\$ or US-20040030123-\$ or US-20030236347-\$ or US-20040195826-\$ or US-20030159764-\$ or US-20030116269-\$ or US-20020111707-\$ or US-20020086104-\$ or US-20020113331-\$ or US-20050227067-\$ or US-20030082315-\$ or US-20040044134-\$ or US-20040247882-\$ or US-20020010288-\$ or US-20020126457-\$ or US-20050057902-\$ or US-20060077643-\$ or US-20040047570-\$ or US-20030053767-\$ or US-20030104729-\$ or US-20040062015-\$).did. or (US-4486466-\$ or US-5364914-\$ or US-4972031-\$ or US-5528155-\$ or US-4042486-\$ or US-3619342-\$ or US-4524161-\$ or US-3919348-\$ or US-3919134-\$ or US-3907724-\$ or US-6314253-\$ or US-6222006-\$ or US-4446257-\$ or US-3617429-\$ or US-3607598-\$ or US-4119679-\$ or US-3616163-\$ or US-4147737-\$ or US-5385957-\$ or US-5540581-\$ or US-5232654-\$ or US-5672305-\$ or US-5464658-\$ or US-5350621-\$ or US-6713598-\$ or US-6415104-\$).did. or (US-4548678-\$ or US-6043333-\$ or US-5743751-\$ or US-5957547-\$ or US-5699235-\$ or US-6282092-\$).did. or (US-3772392-\$ or US-2983630-\$ or US-2935488-\$ or US-3484398-\$ or US-3838087-\$ or US-3300332-\$ or US-3510445-\$ or US-3331891-\$).did.	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/31 07:44
S79	3	S75 S78	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 14:46
S80	26	(molding adj pressure) near (kg or lb)	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 17:06
S81	0	S78 S80	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 16:28
S82	16	((molding adj pressure) near (kg or lb)) resin	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 16:40
S83	6	((molding adj pressure) near (kg or lb)) resin (molding adj temperature)	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 16:40
S84	26	((molding adj pressure) near (kg or lb)) temperature	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/30 17:07

S85	52	(US-20020181211-\$ or US-20040030123-\$ or US-20030236347-\$ or US-20030159764-\$ or US-20030116269-\$ or US-20020111707-\$ or US-20020086104-\$ or US-20020113331-\$ or US-20040044134-\$ or US-20040247882-\$ or US-20020010288-\$ or US-20020126457-\$ or US-20050057902-\$ or US-20060077643-\$ or US-20040047570-\$ or US-20030053767-\$ or US-20030104729-\$ or US-20040062015-\$).did. or (US-5364914-\$ or US-4042486-\$ or US-3619342-\$ or US-4524161-\$ or US-3919348-\$ or US-3907724-\$ or US-6314253-\$ or US-6222006-\$ or US-4446257-\$ or US-3617429-\$ or US-4119679-\$ or US-3616163-\$ or US-4147737-\$ or US-5385957-\$ or US-5540581-\$ or US-5672305-\$ or US-5464658-\$ or US-6415104-\$ or US-4548678-\$ or US-6043333-\$ or US-5743751-\$ or US-5957547-\$ or US-5699235-\$ or US-6282092-\$ or US-5571854-\$ or US-6365243-\$).did. or (US-3772392-\$ or US-2983630-\$ or US-2935488-\$ or US-3484398-\$ or US-3838087-\$ or US-3300332-\$ or US-3510445-\$ or US-3331891-\$).did.	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/31 07:35
S86	3313	361/785,704,717,753,760,803.cor. 525/438,524,546,705.cor. 428/182.cor.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/31 08:01
S87	7624	(device or package) ((connector) near (PCB or wcb or ((circuit or wiring) adj board)))	US-PGPUB; USPAT; USOCR, FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/31 08:02
S88	88	S86 S87	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/31 08:02
S89	38	connector (PCB or wcb or ((circuit or wiring) adj board)) (thermoset\$4 adj resin) (solid near resin)	US-PGPUB; USPAT; USOCR, FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2007/10/31 08:03
S90	0	S89 S88	US-PGPUB; USPAT; USOCR	AND	ON	2007/10/31 08:03
S91	13359	resin with (solid or suring) with temperature	US-PGPUB; USPAT; USOCR	AND	ON	2008/02/16 14:57
S92	52	(US-20020181211-\$ or US-20040030123-\$ or US-20030236347-\$ or US-20030159764-\$ or US-20030116269-\$ or US-20020111707-\$ or US-20020086104-\$ or US-20020113331-\$ or US-20040044134-\$ or US-20040247882-\$ or US-20020010288-\$ or US-20020126457-\$ or US-20050057902-\$ or US-20060077643-\$ or US-20040047570-\$ or US-20030053767-\$ or US-20030104729-\$ or US-20040062015-\$).did. or (US-5364914-\$ or US-4042486-\$ or US-3619342-\$ or US-4524161-\$ or US-3919348-\$ or US-3907724-\$ or US-6314253-\$ or US-6222006-\$ or US-	US-PGPUB; USPAT; USOCR	AND	ON	2008/02/16 14:57

		4446257-\$ or US-3617429-\$ or US-4119679-\$ or US-3616163-\$ or US-4147737-\$ or US-5385957-\$ or US-5540581-\$ or US-5672305-\$ or US-5464658-\$ or US-6415104-\$ or US-4548678-\$ or US-6043333-\$ or US-5743751-\$ or US-5957547-\$ or US-5699235-\$ or US-6282092-\$ or US-5571854-\$ or US-6365243-\$).did. or (US-3772392-\$ or US-2983630-\$ or US-2935488-\$ or US-3484398-\$ or US-3838087-\$ or US-3300332-\$ or US-3510445-\$ or US-3331891-\$).did.				
S93	21	S91 S92	US-PGPUB; USPAT; USOCR	AND	ON	2008/02/16 14:57

2/ 17/ 2008 10:53:45 AM

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